



Part Number : 783150001

Product Description : 1.00mm Pitch Aerodynamic DDR3 DIMM Socket, Very Low Profile, Vertical, Press-Fit, with Pegs, Black Housing and Latches, 0.76µm Gold (Au) Plating, 1.85mm Compliant Pin Length, 2.40mm PCB Thickness, 240 Circuits, Lead-Free



Series Number : 78315

Status : Active

Product Category : Memory Module Connectors

Documents & Resources

Drawings

Drawing 783150001_sd.pdf

3D Models and Design Files

3D Model 783150001_stp.zip

Electrical Model Document EE-78315-002-001.pdf

Electrical Model Document EE-78315-003-001.pdf

S-Parameter Model SP-78315-002-001.zip

S-Parameter Model SP-78315-003-001.zip

Specifications

Application Specification AS-78315-001-001.pdf

Product Specification PS-78315-001-001.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	
EU ELV	Not Relevant
Low-Halogen Status	Not Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2023)3788-DC (14 Jun 2023)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	Active
Category	Memory Module Connectors
Series	78315
Description	1.00mm Pitch Aerodynamic DDR3 DIMM Socket, Very Low Profile, Vertical, Press-Fit, with Pegs, Black Housing and Latches, 0.76µm Gold (Au) Plating, 1.85mm Compliant Pin Length, 2.40mm PCB Thickness, 240 Circuits, Lead-Free
Component Type	Socket
JEDEC Outline	SO-012
Product Family	DDR3 DIMM Sockets
Product Name	DDR3 DIMM
UPC	800756929507

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	1.0A
Voltage Key	Center
Voltage - Maximum	30V AC (RMS)/DC

Physical

Circuits (Loaded)	240
Circuits (maximum)	240
Durability (mating cycles max)	25
Entry Angle	Vertical
Flammability	94V-0
Housing Color	Black
Keying to Mating Part	Yes
Latch Color	Black
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	Nylon
Net Weight	7.501/g
Packaging Type	Tray
PC Tail Length	1.85mm
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness - Recommended	2.40mm
Pitch - Mating Interface	1.00mm
Pitch - Termination Interface	1.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.381µm
Temperature Range - Operating	-55° to +85°C
Termination Interface Style	Through Hole - Compliant Pin

Solder Process Data

Lead-Free Process Capability	N/A
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Mates With / Use With

Mates with Part(s)

Description	Part Number
Mates With	JEDEC Standard 1.27mm Modules

Application Tooling

Global

Description	Part Number
DDR3 DIMM Memory Module Extraction Tool	<u>0622023800</u>

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